ABSTRACT

HOLLOW WALLBOARD AND PROCESSING METHOD THEREOF

The embodiment of the present disclosure discloses a hollow wallboard and a processing method thereof, which includes: an upper substrate, a lower substrate and a covering layer. The upper substrate has a veneer and a backside, and the covering layer is attached to the veneer, a plurality of ribs are provided on the backside, the lower substrate is attached to the plurality of ribs, and is arranged opposite to the upper substrate. The temperature stress of the lower substrate to the upper substrate is equal to that of the covering layer to the upper substrate. Using the embodiment of the present disclosure can make the lower substrate overcome the deformation problem caused by the temperature difference of the single-sided covering wallboard, and ensure the flatness of the wallboard. All parts can be industrialized in the factory, and only simple assembly is required on site. The structure is simple and the weight is small, which can not only improve the installation efficiency, but also reduce the technical requirements for the installation workers and reduce the labor cost. At the same time, the wallboard does not need to be bonded on site, which is environmentally friendly and pollution-free.

Figure 1